



Material Content Data Sheet



Sales Product Name		SAK-XC161CS-32F40F BB-A		Issued		29. August 2013		
MA#		MA000964764						
Package		PG-TQFP-144-7		Weight*		1402.20 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	33.010	2.35	2.35	23541	23541
leadframe	non noble metal	magnesium	7439-95-4	0.529	0.04		377	
	inorganic material	silicon	7440-21-3	2.293	0.16		1635	
	non noble metal	nickel	7440-02-0	10.581	0.75		7546	
wire	non noble metal	copper	7440-50-8	339.310	24.20	25.15	241985	251543
	noble metal	gold	7440-57-5	3.590	0.26	0.26	2560	2560
	encapsulation	organic material	carbon black	1333-86-4	4.981	0.36		3552
encapsulation	plastics	epoxy resin	-	134.483	9.59		95909	
	inorganic material	silicondioxide	60676-86-0	856.707	61.10	71.05	610975	710436
leadfinish	non noble metal	tin	7440-31-5	8.638	0.62	0.62	6160	6160
plating	noble metal	silver	7440-22-4	4.833	0.34	0.34	3447	3447
glue	plastics	epoxy resin	-	0.649	0.05		463	
	noble metal	silver	7440-22-4	2.595	0.18	0.23	1850	2313
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com